

# Zener Diode DZ5S068D0R

### DZ5S068D0R Silicon epitaxial planar type

For surge absorption circuit DZ5J068D in SSMini5 type package

#### Features

- · Excellent rising characteristics of zener current Iz
- Low zener operating resistance RzHalogen-free / RoHS compliant
  - (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol:02
- Basic Part Number : Dual DZ3X068D (Common anode)

Packaging Embossed type (Thermo-compression sealing) 8 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C

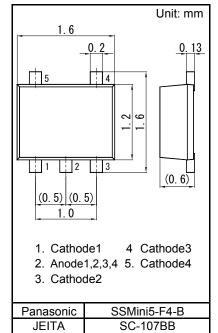
Parameter	Symbol	Rating	Unit
Total power dissipation <sup>*1</sup>	PT	150	mW
Electrostatic discharge *2	ESD	±10	kV
Junction temperature	Tj	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +150	°C

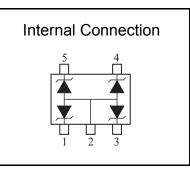
Storage temperatureTstg-55to+150Note)\*1: Mounted on glass epoxy print board. (45 mm x 45 mm x 1 mm)

(4Diode total)

Solder in ( 0.35 mm x 0.40 mm)

\*2: Test method:IEC61000\_4\_2(C = 150 pF,R = 330 Ω, Contact discharge:10 times)





SOT-665

Code

#### ■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit	
Forward voltage	VF	IF = 10 mA			1.0	V	
Zener voltage *1, *2	VZ	IZ = 5 mA	6.46		7.14	V	
Zener operating resistance	RZ	IZ = 5 mA			30	Ω	
Zener rise operating resistance	RZK	IZ = 0.5 mA			60	Ω	
Reverse current	IR	VR = 4 V			0.1	μA	
Temperature coefficient of zener voltage *3	SZ	IZ = 5 mA		3.1		mV/°C	

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

2. \*1: The temperature must be controlled 25°C for VZ mesurement.

VZ value measured at other temperature must be adjusted to VZ (25°C)

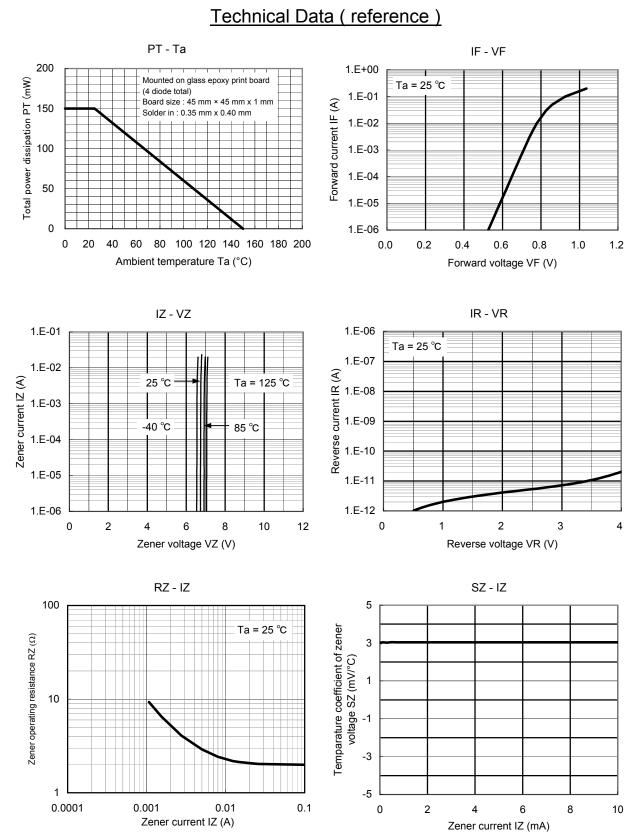
\*2: VZ guaranted 20 ms after current flow.

\*3: Tj = 25°C to 150°C





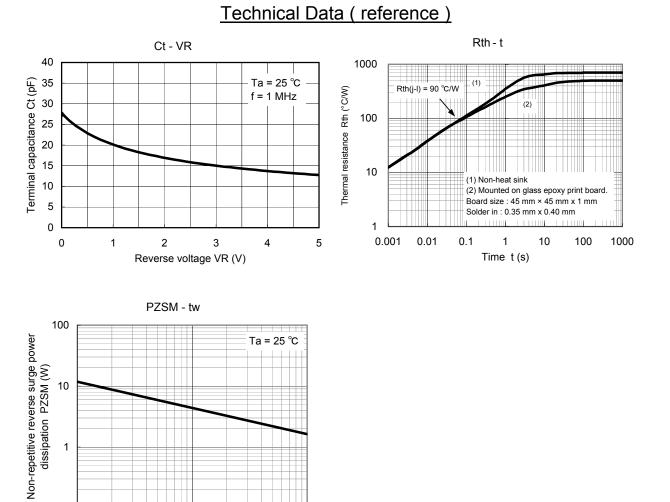
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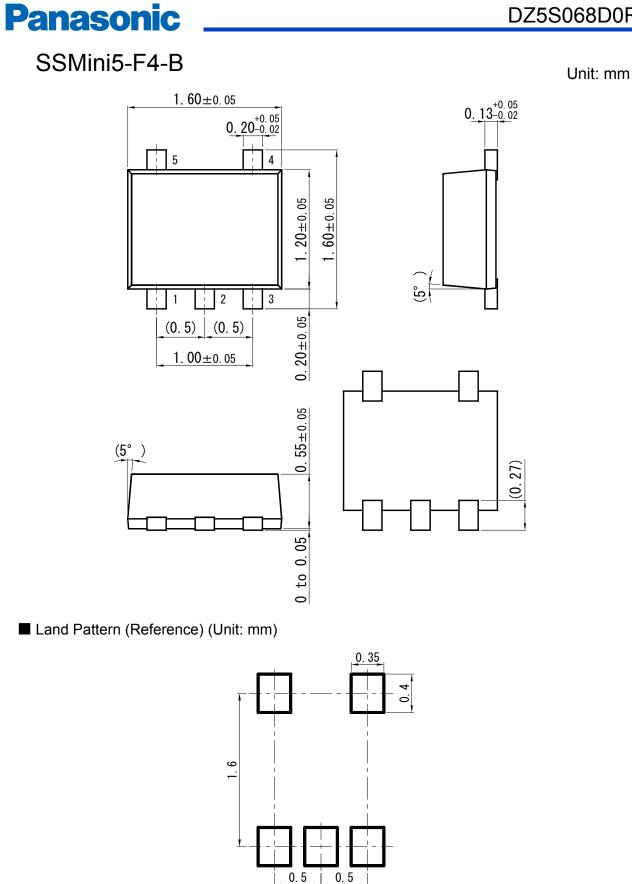


10000

0.1 └ 100

1000

Pulse width tw (µs)



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